Product Change Notification: BLAS-21SMFQ723

Date:

18-Sep-2025

Product Category:

16-Bit - Microcontrollers And Digital Signal Controllers, 16-Bit Microcontrollers, 8-Bit Microcontrollers, Analog to Digital Converters, Backlight LED Drivers, Battery Management and Fuel Gauges - Battery Chargers, CAN Controller, Capacitive Touch Sensors, Clock And Timing - Clock And Data Distribution, Clock And Timing - Clock Generation, Clock And Timing - High Speed Communication, Clock Buffers, CPU / System Supervisors, Digital Potentiometers, Digital Signal Controllers, Digital Temperature Sensors, EL Backlight Driver ICs, Ethernet Controllers, Ethernet Phys, General Purpose LED Drivers, Interface- Serial Peripherals, LIN Transceiver With Vreg, Linear Comparators, Linear Op Amps, Linear Regulators, Memory, Motor Drivers, Power Management - PMIC, Power Management - Power Switches, Power Management - PWM Controllers, Power Management - System Supervisors/Voltage Detectors, Power Management - Terminators, Power MOSFET Drivers, Switching Regulators, Wireless IC

Notification Subject:

CCB 6462 Final Notice: Qualification of UNIG as a new assembly site for various products available in Tube, Tray and Tape & Reel packing media.

Affected CPNs:

BLAS-21SMFQ723_Affected_CPN_09182025.pdf
BLAS-21SMFQ723_Affected_CPN_09182025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of UNIG as a new assembly site for various products available in Tube, Tray and Tape & Reel packing media.

Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	Unisem (M) Berhad Perak, Malaysia (UNIS)	Unisem Gopeng (UNIG)
Wire Material	Au	Au
Die Attach Material	8290	8290
Molding Compound Material	G770HCD	G770HCD
Lead-Frame Material	A194ESH	A194ESH

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying UNIG as a new assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 June 2025 (date code: 2527)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	November 2023					**>**	**May 2025**					**June 2025**				
Workweek	44	45	46	47	48		18	19	20	21	22	23	24	25	26	27
Initial PCN Issue Date				x												
Qual Report Availability											x					
Final PCN Issue Date											x					
Estimated Implementation Date																x

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

November 22, 2023: Issued initial notification.
October 31, 2024: Re-issued initial notification. Updated the qualification plan to include High Temperature Storage Life (HTSL) test. Updated the affected CPN list to remove the EOL'd CPNs. Updated the estimated qualification completion date and the timetable summary from June 2024 to October 2024.
May 30, 2025: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 30, 2025. Updated affected CPN list based on the updated scope to remove selected 93LCxx, 93AAxx, 93C4xx, MCP6xx, 93C8xx, 93C7xx, 24C0xx, MCP1xx, 93C6xx, 24FCxx, SY88xx, PIC1xx, MIC5xx, SY58xx, SY89xx, 93C5xx, 24LCxx, 24AAxx, 34AAxx, 25LCxx, 25AAxx, SPN1xx and MICRxx device families and to add selected MIC46xx, SM802xx, SM803xx, MIC52xx, MIC53xx, MIC82xx, MIC27xx, MIC26xx, MIC84xx, MIC20xx, MIC94xx, MIC22xx, MIC23xx, MIC28xx, MIC44xx, PIC12xx, PIC16xx, PIC18xx and dsPIC33FJ32MC202 device families.
September 18, 2025: Re-issued final notification to update the Qualification Report to include wire bond pull, wire bond shear and solderability test results. Updated affected CPN list to remove EOL'd CPNs.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_BLAS-21SMFQ723-Qualification_Report_.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

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